

- Water-resistant wood adhesive (D3)
- Developed for bonding FixChip®, but also universally applicable
- Apply with bottle, brush, glue comb, glue roller, or glue gun (pressure barrel)
- Press using hot or cold presses, clamps with glue clamps
- Paintable
- KOMO certified according to Interior class D3, certificate no. 33196

## PRODUCT

Universal, solvent-free, water-resistant ready-to-use wood glue with a short setting time and rapid strength development. Suitable for interior applications.

## SAMENSTELLING EN EIGENSCHAPPEN

Base	: PVAc
Solid content	: approx. 48 ± 1%
Density (20°C)	: approx. 1.05 g/cm <sup>3</sup>
Viscosity	: approx. 12,000 mPa.s
pH (25°C)	: 3-3.5
Minimum processing temperature	: 5-7°C
Whitpoint	: approx. 6°C
Colour (wet)	: white
Colour (dry)	: translucent
Odour	: typical (slightly acidic)
Number of components	: 1
Temperature resistance	: -20°C to +80°C
Moisture resistance	: according to NEN-EN 204 D3
Open time	: 100 gr/m <sup>2</sup> max. 4 minutes 200 gr/m <sup>2</sup> max. 10 minutes
Consumption	: 100 - 200 g/m <sup>2</sup>
Shear strength	: 150 kg/cm <sup>2</sup>

ATTENTION: The above values are determined at 20°C / 65% RH and a wood moisture content of 10%. Deviating conditions may result in different values.

## APPLICATION

FixChip D3® is suitable for bonding FixChip® and FixChip® Mini, as well as for structural and panel joints. In addition to FixChips, the adhesive is universally suitable for standard assembly bonding. FixChip D3® can also be used for bonding in humid environments, such as bathrooms and kitchens.

FixChip® D3 adhesive is suitable for bonding hardwoods, softwoods, and exotic wood species, as well as veneer and thermoset plastic sheets (Duropal, Print HPL, Formica, Resopal, etc.), CPL foil, particleboard, plywood, MDF, hardboard, and all other wood-based materials.

## PROCESSING / APPLICATION INSTRUCTIONS

Both surfaces to be bonded must be dry, clean, and free of dust and grease. Apply the adhesive according to the instructions in the FixChip® manual. Apply a small amount of glue in both grooves. Join the pieces and maintain a clamping time of 5 minutes, followed by a resting period of 30 minutes.

It is recommended to perform the bonding using clamps or in a press (pressing pressure 1–6 kg/cm<sup>2</sup>). Remove wet adhesive immediately with a damp cloth; cured adhesive can be removed mechanically. If desired, the adhesive can be diluted with up to 3% water.

## MATERIAL SAFETY DATA SHEET

For up-to-date and detailed information regarding chemical composition, safety aspects, handling, transport, storage, personal protection, and related topics, please refer to the Material Safety Data Sheet (MSDS) for this product. Your supplier has the most recent version of the document, and it can also be requested from Frencken.

## SHELF LIFE

For information on shelf life, please refer to the packaging.



FixChip® D3



This Product Data Sheet replaces all previous versions. The above product information and recommendations are entirely non-binding and based on extensive test measurements and experience. However, due to the use of new materials, different working methods, and other factors beyond Frencken's control, Frencken cannot accept any liability. Please consult the website for the current version. If in doubt, please contact Frencken.